

## General Description

The GreenMOS® high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

The GreenMOS® Z series is integrated with fast recovery diode (FRD) to minimize reverse recovery time. It is suitable for resonant switching topologies to reach higher efficiency, higher reliability and smaller form factor.

## Features

- Low  $R_{DS(ON)}$  & FOM
- Extremely low switching loss
- Excellent stability and uniformity



## Applications

- LED lighting
- Telecom
- Adapter
- Sever
- Solar/UPS

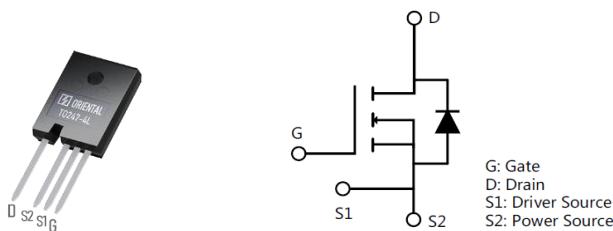
## Key Performance Parameters

Parameter	Value	Unit
$V_{DS}$	600	V
$I_D$ , pulse	348	A
$R_{DS(ON)}$ , max @ $V_{GS}=10V$	17	mΩ
$Q_g$	189	nC
PD	680	W

## Marking Information

Product Name	Package	Marking
OSG60R017H4T4EZF	TO247-4L	OSG60R017H4T4EZ

## Package & Pin Information



**Absolute Maximum Ratings** at  $T_j=25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	$V_{DS}$	600	V
Gate-source voltage (static)	$V_{GS}$	$\pm 20$	V
Gate-source voltage (dynamic)		$\pm 30$	V
Continuous drain current <sup>1)</sup> , $T_C=25^\circ\text{C}$	$I_D$	116	A
Continuous drain current <sup>1)</sup> , $T_C=100^\circ\text{C}$		73.4	
Pulsed drain current <sup>2)</sup> , $T_C=25^\circ\text{C}$	$I_{D, \text{pulse}}$	348	A
Continuous diode forward current <sup>1)</sup> , $T_C=25^\circ\text{C}$	$I_S$	116	A
Diode pulsed current <sup>2)</sup> , $T_C=25^\circ\text{C}$	$I_{S, \text{pulse}}$	348	A
Power dissipation <sup>3)</sup> , $T_C=25^\circ\text{C}$	$P_D$	680	W
Single pulsed avalanche energy <sup>4)</sup>	$E_{AS}$	2250	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0\dots 400\text{ V}$	dv/dt	100	V/ns
Reverse diode dv/dt, $V_{DS}=0\dots 400\text{ V}$ , $I_{SD} \leq I_D$	dv/dt	50	V/ns
Operation and storage temperature	$T_{stg}, T_j$	-55 to 150	$^\circ\text{C}$

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	0.18	$^\circ\text{C}/\text{W}$
Thermal resistance, junction-ambient	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$

**Electrical Characteristics** at  $T_j=25^\circ\text{C}$  unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	$BV_{DSS}$	600			V	$V_{GS}=0\text{ V}$ , $I_D=2\text{ mA}$
Gate threshold voltage	$V_{GS(\text{th})}$	3		4.5	V	$V_{DS}=V_{GS}$ , $I_D=2\text{ mA}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		15	17	$\text{m}\Omega$	$V_{GS}=10\text{ V}$ , $I_D=58\text{ A}$
			41			$V_{GS}=10\text{ V}$ , $I_D=58\text{ A}$ , $T_j=150^\circ\text{C}$
Gate-source leakage current	$I_{GS}$			100	$\text{nA}$	$V_{GS}=20\text{ V}$
				-100		$V_{GS}=-20\text{ V}$
Drain-source leakage current	$I_{DS}$			10	$\mu\text{A}$	$V_{DS}=600\text{ V}$ , $V_{GS}=0\text{ V}$
Gate resistance	$R_G$		1.4		$\Omega$	$f=1\text{ MHz}$ , Open drain

### Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C <sub>iss</sub>		11400		pF	V <sub>GS</sub> =0 V, V <sub>DS</sub> =50 V, f=100 kHz
Output capacitance	C <sub>oss</sub>		604		pF	
Reverse transfer capacitance	C <sub>rss</sub>		2.6		pF	
Effective output capacitance, energy related	C <sub>o(er)</sub>		382		pF	
Effective output capacitance, time related	C <sub>o(tr)</sub>		2310		pF	V <sub>GS</sub> =0 V, V <sub>DS</sub> =0 V-400 V
Turn-on delay time	t <sub>d(on)</sub>		42.4		ns	V <sub>GS</sub> =10 V, V <sub>DS</sub> =400 V, R <sub>G</sub> =2 Ω, I <sub>D</sub> =58 A
Rise time	t <sub>r</sub>		16		ns	
Turn-off delay time	t <sub>d(off)</sub>		96.8		ns	
Fall time	t <sub>f</sub>		2.8		ns	

### Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q <sub>g</sub>		189		nC	V <sub>GS</sub> =10 V, V <sub>DS</sub> =400 V, I <sub>D</sub> =58 A
Gate-source charge	Q <sub>gs</sub>		60		nC	
Gate-drain charge	Q <sub>gd</sub>		52.5		nC	
Gate plateau voltage	V <sub>plateau</sub>		6		V	

### Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V <sub>SD</sub>			1.3	V	I <sub>S</sub> =116 A, V <sub>GS</sub> =0 V
Reverse recovery time	t <sub>rr</sub>		213		ns	
Reverse recovery charge	Q <sub>rr</sub>		1.5		μC	
Peak reverse recovery current	I <sub>rrm</sub>		12.4		A	

### Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) V<sub>DD</sub>=100 V, V<sub>GS</sub>=10 V, L=80 mH, starting T<sub>j</sub>=25 °C.

## Electrical Characteristics Diagrams

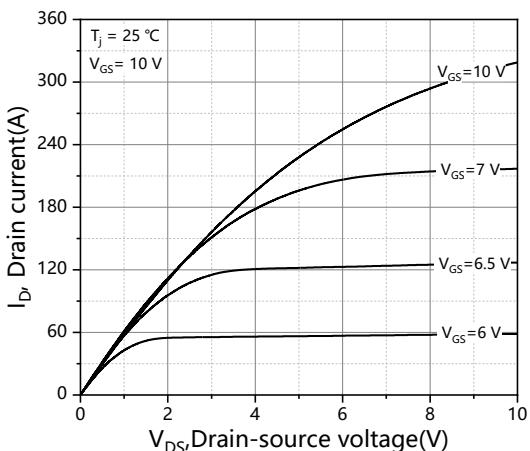


Figure 1. Typ. output characteristics  $T_j=25^\circ\text{C}$

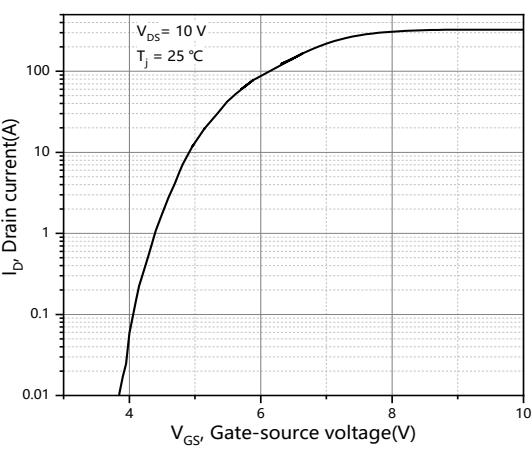


Figure 2. Typ. transfer characteristics

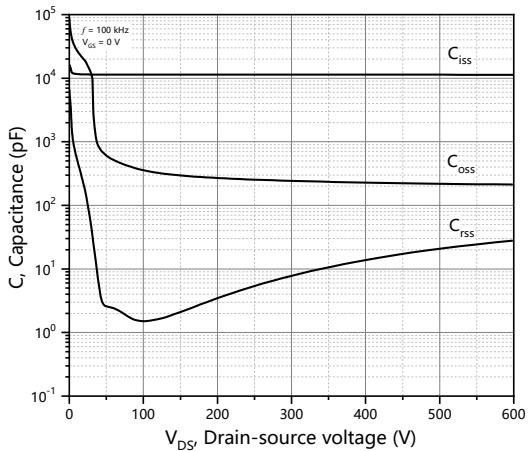


Figure 3. Typ. capacitances

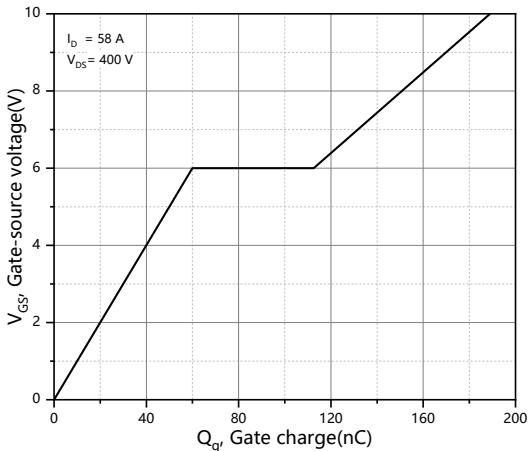


Figure 4. Typ. gate charge

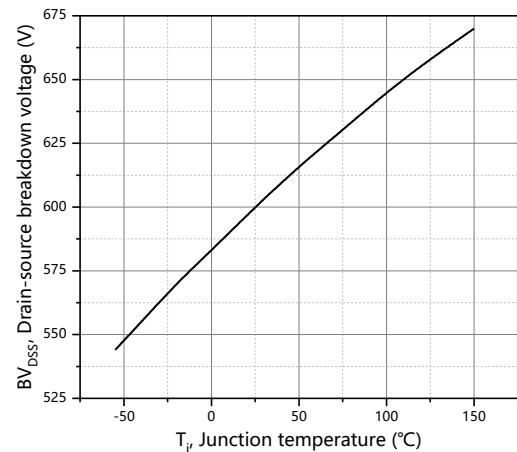


Figure 5. Drain-source breakdown voltage

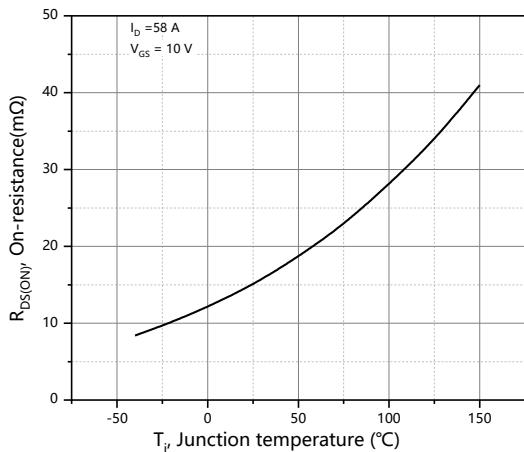
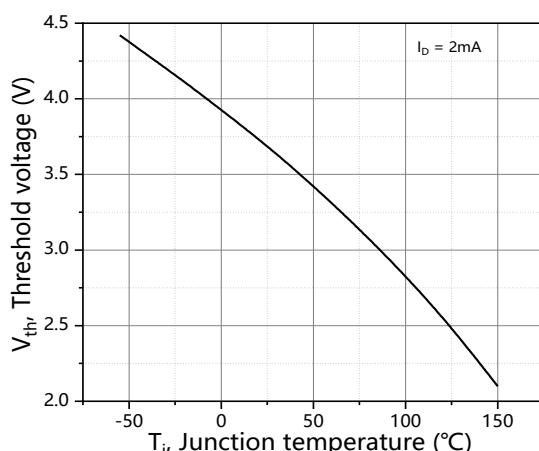
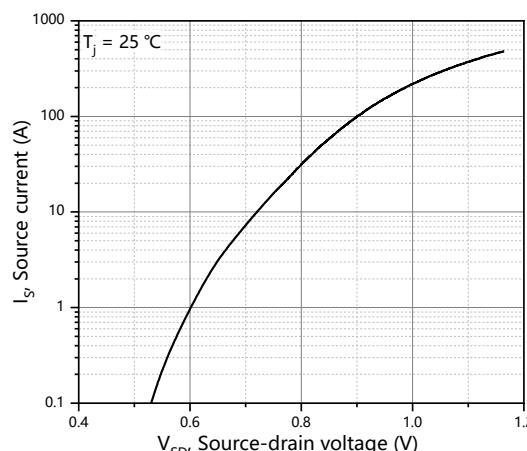
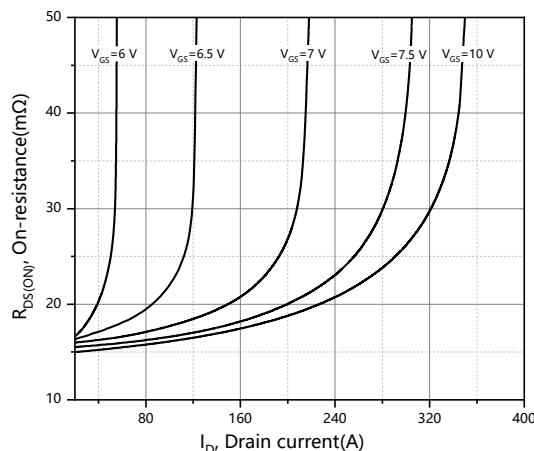
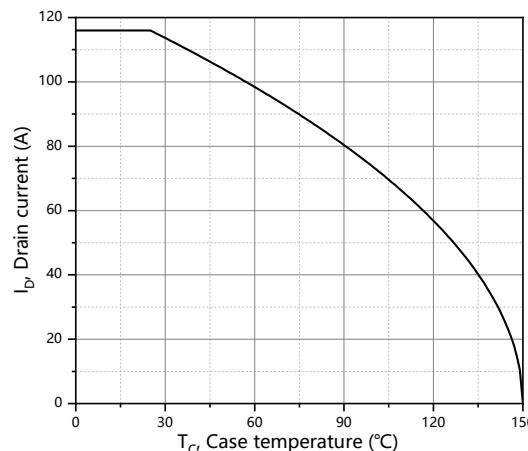
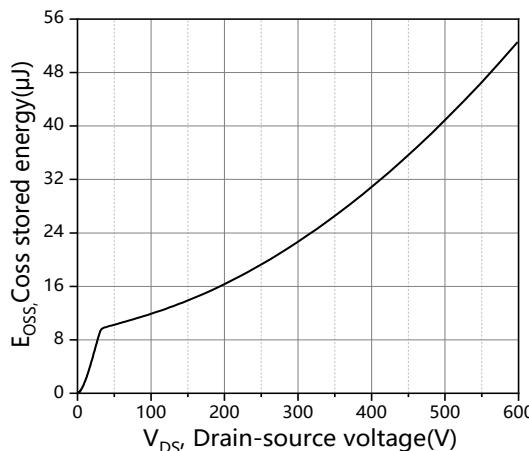
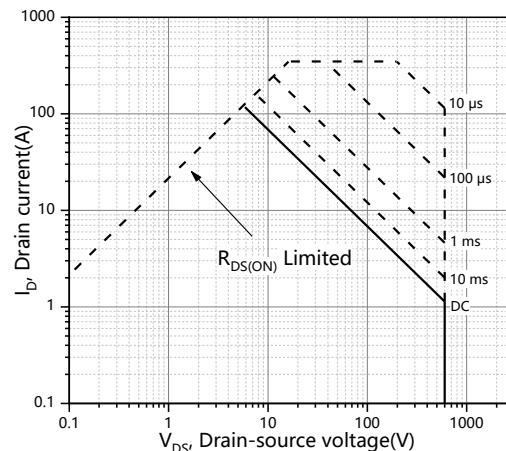


Figure 6. Drain-source on-state resistance


**Figure 7. Threshold voltage**

**Figure 8. Forward characteristic of body diode**

**Figure 9. Drain-source on-state resistance**

**Figure 10. Drain current**

**Figure 11. Typ. Coss stored energy**

**Figure 12. Safe operation area  $T_c=25^\circ\text{C}$**

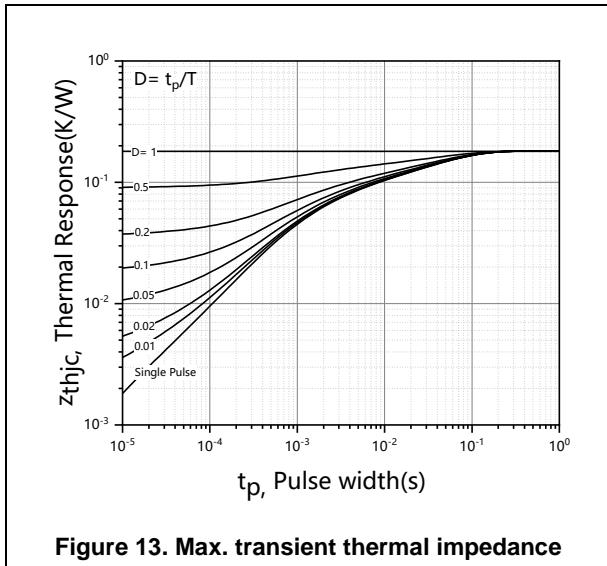
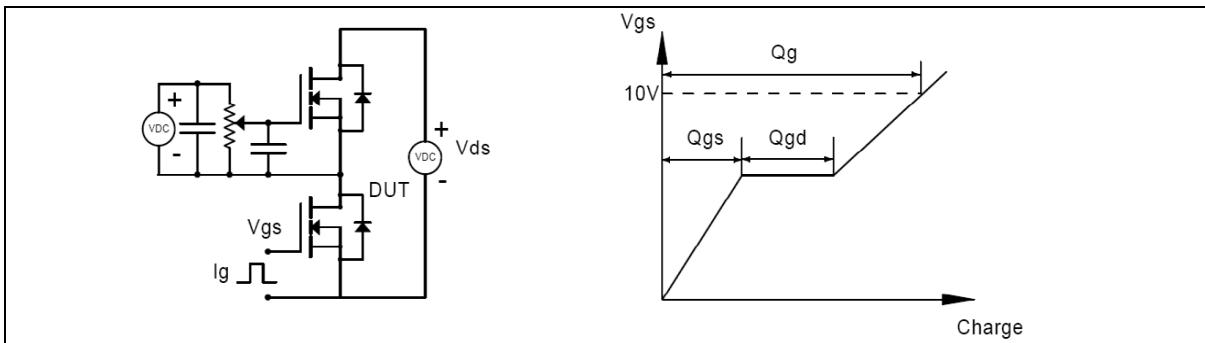
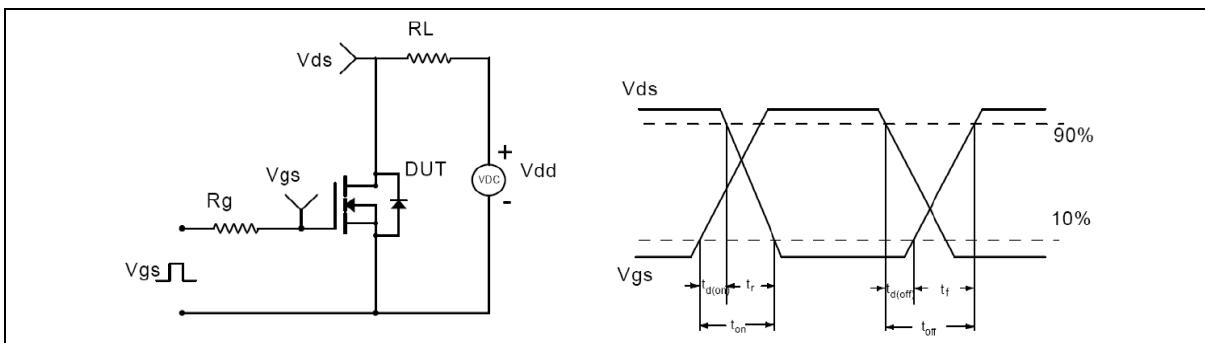


Figure 13. Max. transient thermal impedance

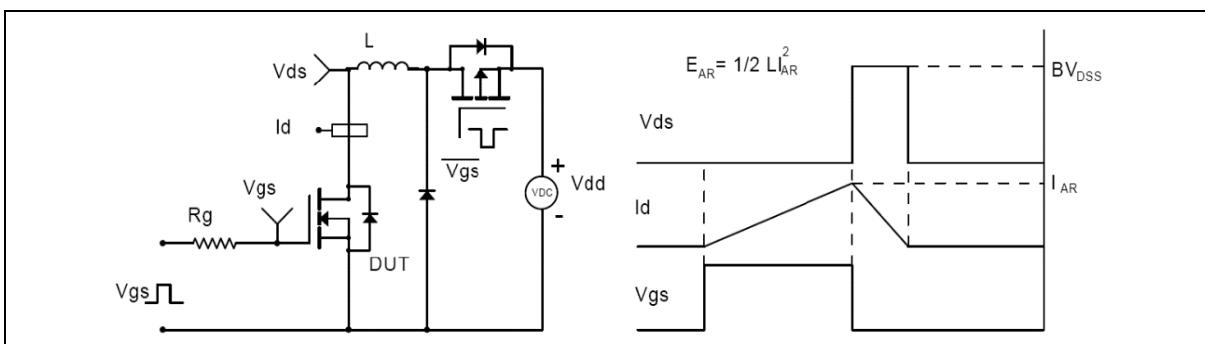
### Test circuits and waveforms



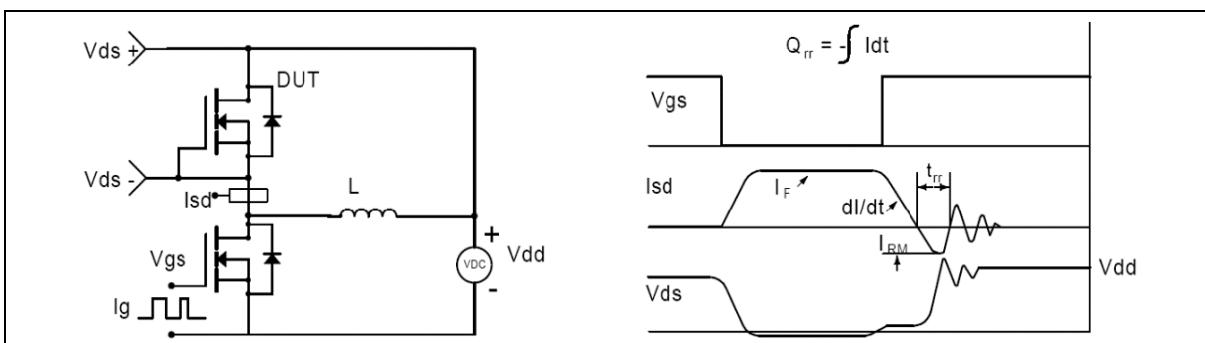
**Figure 1. Gate charge test circuit & waveform**



**Figure 2. Switching time test circuit & waveforms**

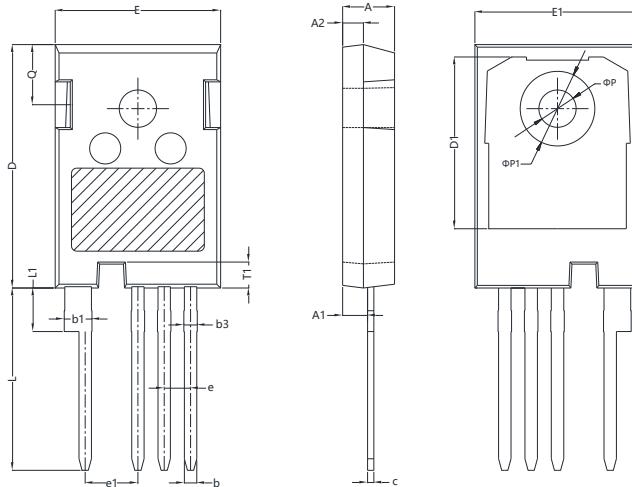


**Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms**



**Figure 4. Diode reverse recovery test circuit & waveforms**

## Package Information



Symbol	mm		
	Min	Nom	Max
A	4.83	5.00	5.20
A1	2.21	2.41	2.61
A2	1.80	2.00	2.20
b	1.06	1.21	1.36
b1	2.33	2.63	2.93
b3	1.07	1.30	1.60
c	0.51	0.61	0.75
D	23.30	23.45	23.60
D1	16.25	16.55	16.85
E	15.74	15.94	16.14
E1	13.72	14.02	14.32
T1	2.35	2.50	2.65
e	2.54 BSC		
e1	5.08 BSC		
Q	5.49	5.79	6.09
L	17.27	17.57	17.87
L1	3.99	4.19	4.39
ΦP	3.40	3.60	3.80
ΦP1	7.19 REF		

Version: TO247-4L-P package outline dimension

## Ordering Information

Package Type	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
TO247-4L-P	30	11	330	6	1980

## Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG60R017H4T4EZF	TO247-4L	yes	yes	yes

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